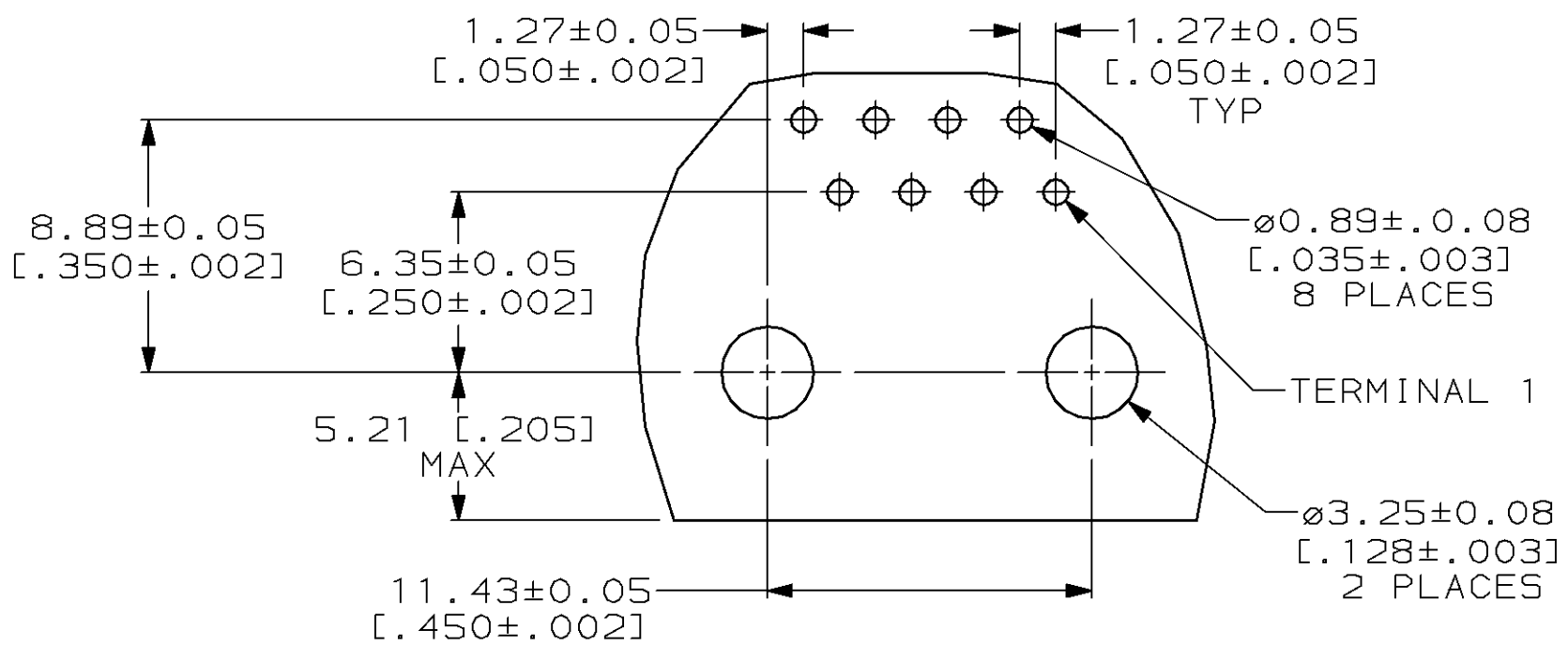
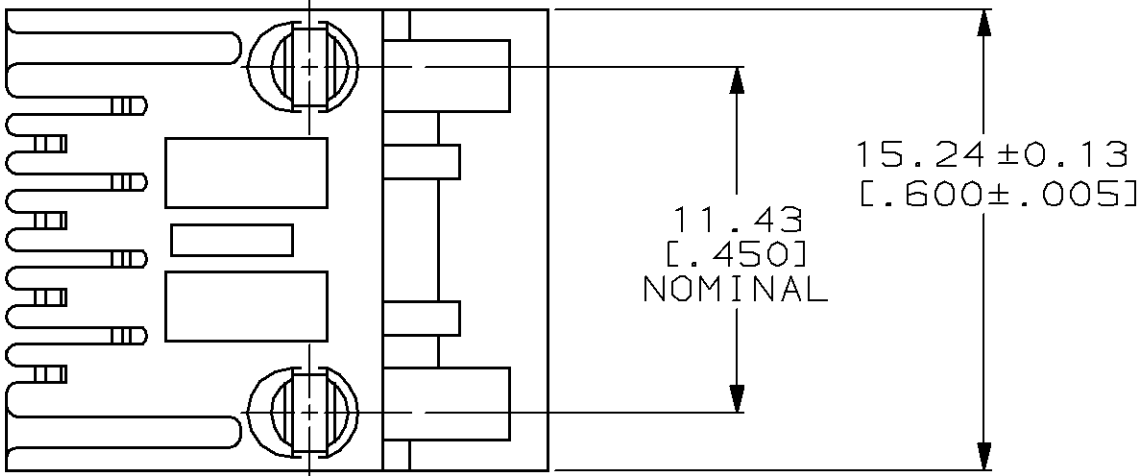
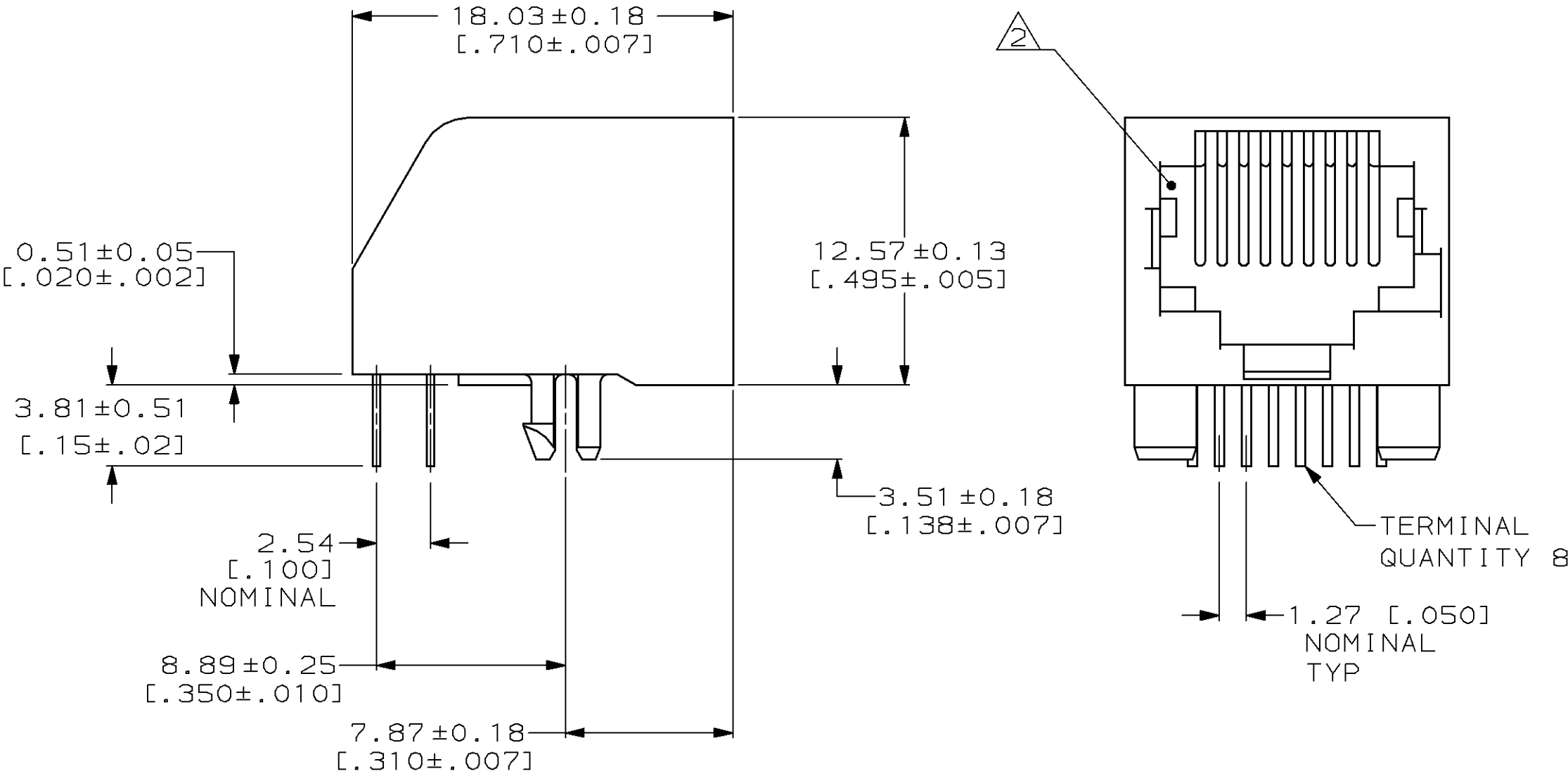


LOC	DIST	P	F	REVISIONS				DATE	APPD
				ZONE	LTR	DESCRIPTION			
AA	22				B	REV; EC 0210-0520-96		05NOV96	DS KW



SUGGESTED PRINTED CIRCUIT BOARD
MOUNTING HOLE LAYOUT
LAYOUT SHOWN FROM CIRCUIT SIDE OF BOARD

THIS DRAWING IS A CONTROLLED DOCUMENT FOR
AMP INCORPORATED. IT IS SUBJECT TO CHANGE
AND THE CONTROLLING ENGINEERING ORGANIZATION
SHOULD BE CONTACTED FOR THE LATEST REVISION.

- 1 MATERIAL: HOUSING - HTN MOLDING COMPOUND, 94 V0, BLACK, IR COMPATIBLE. TERMINAL - PHOS BRONZE PLATED WITH 1.27µm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm[.000150] MINIMUM THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm[.000050] MINIMUM THICK NICKEL UNDERPLATE.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- 3. BULK PACKAGED IN A TRAY.
- 4 THIS ASSEMBLY IS SURFACE MOUNTING COMPATIBLE.

						569118-1	
						PART NO	
DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN mm [INCHES] TOLERANCES ON: 2 PLC DEC ± - 3 PLC DEC ± - ANGLES ± -			DR 1-19-95 D.L. DRUMMOND CHK 1-23-95 C. WHITT APPD 1-30-95 J. TONEY APPD 1-30-95 H. McGRATH PRODUCT SPEC 1089-1163			AMP AMP Incorporated Harrisburg, PA 17105-3608	
MATERIAL			FINISH			NAME MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, KEYED, WITHOUT PANEL STOPS	
			APPLICATION SPEC 114-2048			SIZE C	CAGE CODE 00779
			WEIGHT -			DRAWING NO C-569118	
						SCALE 4:1	SHEET 1 OF 1